IN THE CLAIMS:

Claims 9 have been cancelled. Claims 1-8, and 10-16 have been amended herein. All of the pending claims 1 through 16 are presented below. This listing of claims will replace all prior versions and listings in the application. Please enter these claims as amended.

1. (Currently Amended) An encapsulation method for a plurality of electronic devices within a mold cavity in an encapsulation device comprising:

providing a first substrate having a first side, a second side, and at least one electronic component on ~~said~~ the first side of ~~said~~ the first substrate:

providing a second substrate having a first side, second side, and at least one electronic component on ~~said~~ the first side of ~~said~~ the second substrate;

providing upper and lower mating mold plates, each ~~mold plate~~ of ~~said~~ the upper and lower mating mold plates having a mold cavity portion, each ~~said~~ mold cavity portion of ~~said~~ the upper and lower mating mold plates having a feed runner leading thereto from a material supply ~~to said each mold cavity portion~~ and having a vent runner connected thereto for venting ~~said~~ each mold cavity portion, ~~said~~ the ~~each~~ mold cavity portions together comprising ~~said~~ the mold cavity ~~portion~~ of ~~said~~ the encapsulation device;

placing ~~said~~ the first substrate having ~~said~~ the at least one electronic component on ~~said~~ the first side thereof and ~~said~~ the second substrate having ~~said~~ the at least one electronic component on ~~said~~ the first side thereof into ~~said~~ the mold cavity ~~portion~~, ~~said~~ the first substrate and ~~said~~ the second substrate each having ~~said~~ the second side thereof being located between ~~said~~ the upper and lower mating mold plates;

moving ~~said~~ the upper and lower mating mold plates toward each other to form ~~said~~ the mold cavity ~~portion~~, portions of ~~said~~ the upper mating mold plate engaging portions of ~~said~~ the first surface of ~~said~~ the first substrate and portions of ~~said~~ the lower mating mold plate engaging portions of ~~said~~ the first surface of ~~said~~ the second substrate, ~~said~~ the moving of ~~said~~ the upper and lower mating mold plates toward each other causing ~~said~~ the second

side of ~~said~~ the first substrate and ~~said~~ the second side of ~~said~~ the second substrate to have portions thereof in contact;

injecting a first material into ~~said~~ the ~~upper~~ mold cavity portion of the upper mating mold plate and a second material into ~~said~~ the ~~lower~~ mold cavity portion of the lower mating mold plate to separately encapsulate ~~said~~ the at least one electronic component on ~~said~~ the first side of ~~said~~ the first substrate and ~~said~~ the at least one electronic component on ~~said~~ the first side of ~~said~~ the second substrate, ~~said~~ the second material comprising one of the first material ~~or~~ and a similar material; and

removing ~~said~~ the first substrate and ~~said~~ the second substrate from ~~said~~ the upper and lower mating mold plates, ~~said~~ the first substrate and ~~said~~ the second substrate each having at least one encapsulated electronic component on ~~said~~ the first side thereof.

2. (Currently Amended) The method of claim 1, wherein ~~said~~ the injecting ~~said~~ the second material into ~~said~~ the ~~lower~~ mold cavity portion of the lower mating mold plate comprises injecting a material substantially identical to ~~said~~ the first material.

3. (Currently Amended) The method of claim 1, wherein ~~said~~ the injecting ~~said~~ the second material into ~~said~~ the ~~lower~~ mold cavity portion of the lower mating mold plate comprises injection of a material substantially different from ~~said~~ the first material.

4. (Currently Amended) The method of claim 1, wherein ~~said~~ the first material and ~~said~~ the second material are injected substantially simultaneously.

5. (Currently Amended) The method of claim 1, wherein ~~said~~ the first material and ~~said~~ the second material are injected at different times.

6. (Currently Amended) The method of claim 1, further comprising cleaning ~~said~~ the second side of each of ~~said~~ the first substrate and ~~said~~ the second substrate.

7. (Currently Amended) The method of claim 1, further comprising curing ~~said~~ the plurality of electronic devices at an elevated curing temperature.

8. (Currently Amended) An encapsulation method for a plurality of electronic devices within a mold cavity of an encapsulation apparatus, ~~said~~ the method comprising:

providing a first substrate having a first side, a second side, and at least one electronic component located on ~~said~~ the first side of ~~said~~ the first substrate;

providing a second substrate having a first side, a second side, and at least one electronic component located on ~~said~~ the first side of ~~said~~ the second substrate;

providing upper and lower mating mold plates, each ~~mold plate~~ of ~~said~~ the upper and lower mating mold plates having a mold cavity portion, each ~~said~~ mold cavity portion of ~~said~~ the upper and lower mating mold plates having a feed runner leading thereto from a material supply ~~to said each mold cavity portion~~ and having a vent runner connected thereto for venting ~~said~~ each mold cavity portion, ~~said~~ each mold cavity portions together comprising ~~said~~ the mold cavity of ~~said~~ the encapsulation apparatus;

placing ~~said~~ the first substrate having ~~said~~ the at least one electronic component located on ~~said~~ the first side thereof and ~~said~~ the second substrate having ~~said~~ the at least one electronic component located on ~~said~~ the first side thereof into ~~said~~ the mold cavity, ~~said~~ the second side of ~~said~~ the first substrate and ~~said~~ the second side of ~~said~~ the second substrate placed in a back-to-back orientation between ~~said~~ the upper and lower mating mold plates;

moving ~~said~~ the upper and lower mating mold plates to form ~~said~~ the mold ~~cavity~~ cavity, portions of ~~said~~ the upper mating mold plate engaging portions of ~~said~~ the first side of ~~said~~ the first substrate and portions of ~~said~~ the lower mating mold plate engaging portions of ~~said~~ the first side of ~~said~~ the second substrate and causing ~~said~~ the second side of ~~said~~ the first substrate and ~~said~~ the second side of ~~said~~ the second substrate to have portions thereof in engagement;

injecting a first material into ~~said~~ the mold cavity portion of ~~said~~ the upper mating mold plate and a second material into ~~said~~ the mold cavity portion of ~~said~~ the lower mating mold plate to

separately encapsulate ~~said~~ the at least one electronic component ~~mounted~~ located on ~~said~~ the first side of each of ~~said~~ the first and second substrates ~~of said plurality of electronic devices~~, the second material comprising one of the first material and a similar material; and

removing ~~said~~ the plurality of electronic devices from ~~said~~ the mold cavity.

9. (Canceled)

10. (Currently Amended) The method of claim 8, wherein the injecting ~~said~~ the second material into ~~said~~ the ~~lower~~ mold cavity portion of the lower mating mold plate comprises ~~injection of~~ injecting a material substantially identical to ~~said~~ the first material.

11. (Currently Amended) The method of claim 8, wherein ~~the~~ injecting ~~said~~ the second material into ~~said~~ the ~~lower~~ mold cavity portion of the lower mating mold plate comprises ~~injection of~~ injecting a material substantially different from ~~said~~ the first material.

12. (Currently Amended) The method of claim 8, wherein ~~said~~ the first material and ~~said~~ the second material are injected substantially simultaneously.

13. (Currently Amended) The method of claim 8, wherein ~~said~~ the first material and ~~said~~ the second material are injected at different times.

14. (Currently Amended) The method of claim 8, further comprising cleaning ~~said~~ the second side of each of ~~said~~ the first substrate and ~~said~~ the second substrate.

15. (Currently Amended) The method of claim 8, further comprising subjecting ~~said~~ the plurality of electronic devices to a curing temperature.

16. (Currently Amended) The method of claim 8, wherein ~~said~~ the second side of each of ~~said~~ the first substrate and ~~said~~ the second substrate ~~of said electronic device~~ includes solder bumps thereon.